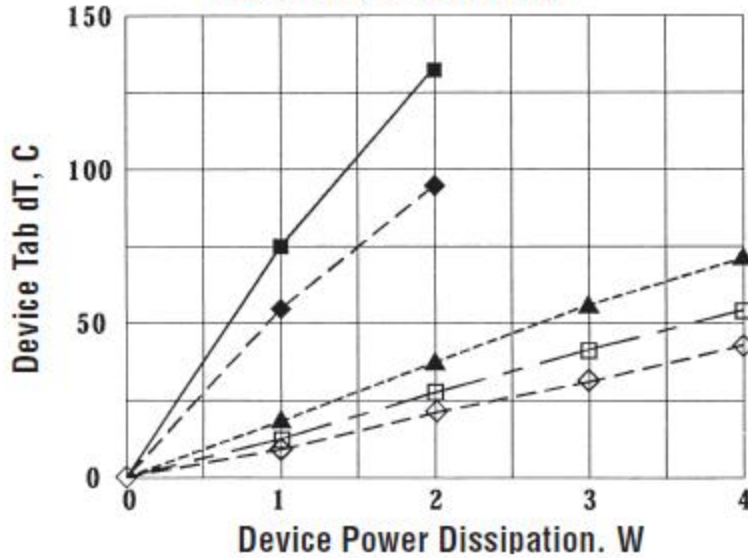
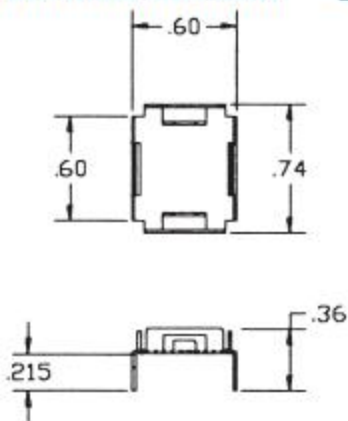


Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Package Format	Package Quantity	Thermal Performance at Typical Load	
					Natural Convection	Forced Convection
217-36CTE6	.360 (9.1)	.600 (15.2) x .740 (18.8)	Bulk	1	55°C @ 1W	16.0°C/W @ 200 LFM
217-36CTTE6	.360 (9.1)	.600 (15.2) x .740 (18.8)	Tube	20	55°C @ 1W	16.0°C/W @ 200 LFM
217-36CTRE6	.360 (9.1)	.600 (15.2) x .740 (18.8)	Tape & Reel	250	55°C @ 1W	16.0°C/W @ 200 LFM

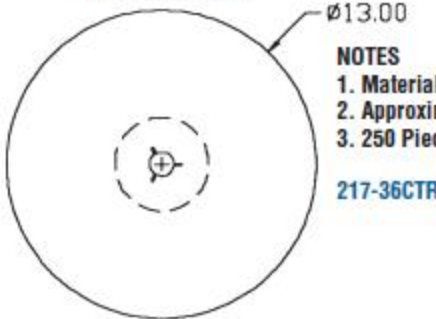
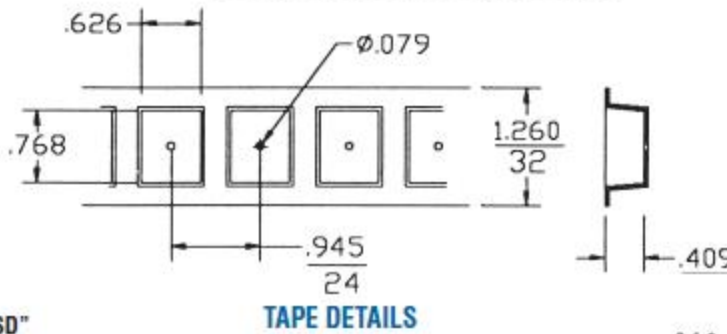
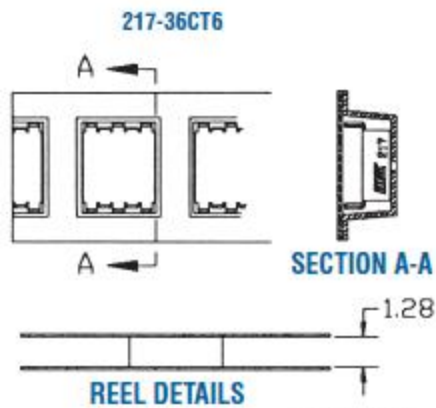
MECHANICAL DIMENSIONS

217 HEAT SINK WITH DDPAK DEVICE

THERMAL PERFORMANCE 6 LAYER BOARD, D'PAK 125°C LEAD, 40°C AMBIENT



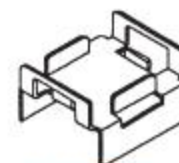
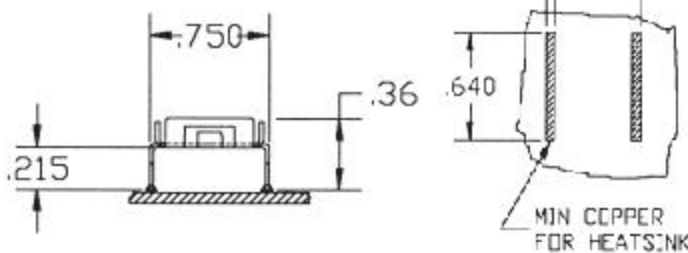
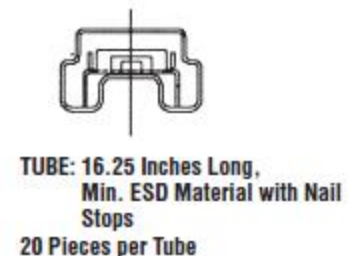
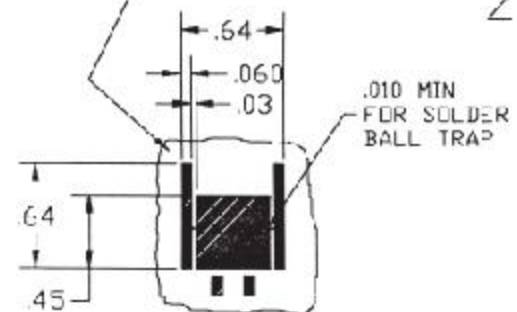
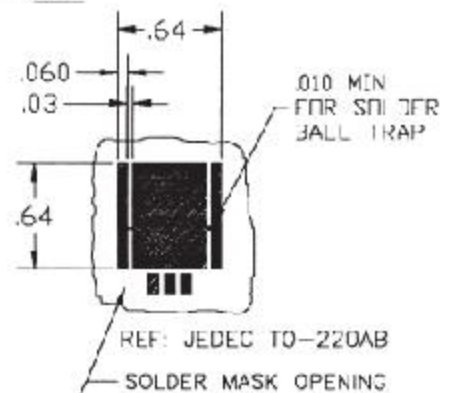
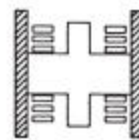
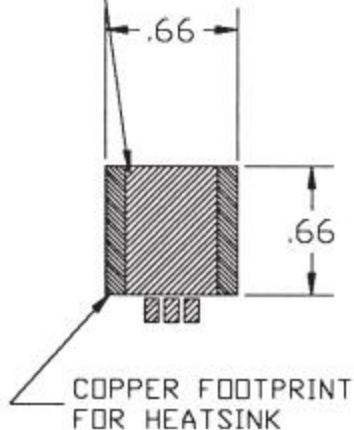
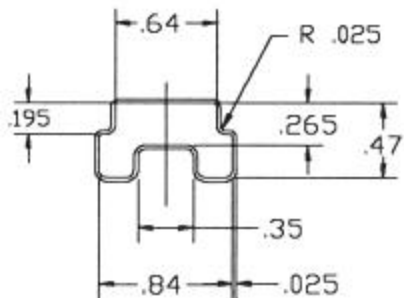
- KEY:
- Device only, NC
 - ◆ Device + HS, NC
 - ▲ Device + HS, 100 lfm
 - Device + HS, 200 lfm
 - ◇ Device + HS, 300 lfm



- NOTES
1. Material to be "ESD"
 2. Approximately 6 Meters per Reel
 3. 250 Pieces per Reel.

BOARD LAYOUT RECOMMENDATIONS

USE MAX COPPER TO ALLOW MAX CONDUCTION TO HEAT SINK



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